

Abstract of the Disclosure

The present photosensitive resin composition 2 comprises a polyamic acid resin 4, a photosensitive agent, a dispersible compound 3 dispersible in the polyamic acid resin 4, and a solvent. The porous resin is obtained by removing the solvent from the photosensitive resin composition 2 to form a composition in which the dispersible compound 3 is dispersed in the polyamic acid resin 4, removing the dispersible compound to make the composition porous, and curing the porous photosensitive resin composition. The porous resin enables forming a fine circuit pattern and has a low dielectric constant and, when used as an insulating layer of a circuit board, brings about improved high frequency characteristics.